

**Change in Packaging Box for the MELSEC iQ-F Series I/O Modules (Extension Cable Type)**

## ■Date of Issue

November 2023

## ■Relevant Models

FX5-16EX/ES, FX5-16EYR/ES, FX5-16EYT/ES, FX5-16EYT/ESS, FX5-16ER/ES, FX5-16ET/ES, FX5-16ET/ESS, FX5-16ET/ES-H, FX5-16ET/ESS-H

Thank you for your continued support of Mitsubishi Electric micro programmable controllers, MELSEC iQ-F series.

This technical bulletin informs you that the size and internal buffering structure of packaging box for the MELSEC iQ-F series I/O modules (extension cable type) will be changed.

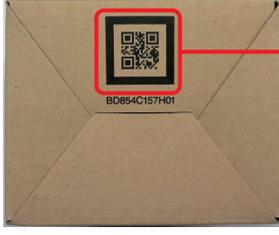
There is no impact on the general specifications, performance specifications, functions, and external dimensions of these modules due to the change.

**1 RELEVANT MODELS**

Product	Model
Input module	FX5-16EX/ES
Output module	FX5-16EYR/ES, FX5-16EYT/ES, FX5-16EYT/ESS
I/O module	FX5-16ER/ES, FX5-16ET/ES, FX5-16ET/ESS
High-speed pulse input/output module	FX5-16ET/ES-H, FX5-16ET/ESS-H

## 2 DETAILS ON THE CHANGE

The size and internal buffering structure of packaging box will be changed as follows. In addition, recycling codes will be changed, and a two-dimensional code will be added.

Item	Before change	After change
External dimensions of packaging box	105 (W) × 92 (D) × 90 (H) [mm]	111 (W) × 92 (D) × 90 (H) [mm]
Form of packaging box		 <ul style="list-style-type: none"> <li>• The shape of the lid will be changed.</li> <li>• The number of buffer parts will be changed from one to two.</li> </ul>
Recycling code Two-dimensional code	  <p style="text-align: center;">Recycling code</p> 	  <p style="text-align: center;">Recycling codes</p>  <p style="text-align: center;">Two-dimensional code</p>

## 3 REASON FOR THE CHANGE

To improve the packaging quality.

## 4 SCHEDULE

The change will be applied to products manufactured in December 2023 and after.

Note that, depending on stock status, both products with packaging before and after change may be distributed in the market around that time.

We appreciate your kind understanding.

### REVISIONS

Version	Date of Issue	Revision
A	November 2023	First edition

### TRADEMARKS

The company names, system names, and product names mentioned in this technical bulletin are either registered trademarks or trademarks of their respective companies.

In some cases, trademark symbols such as "™" or "®" are not specified in this technical bulletin.